



Kester to Present at the Contamination, Cleaning and Coating Conference

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On Tuesday, May 23, Kester's Bruno Tolla and Kyzen's Mike Bixenman will present "Impact of Reflow and Cleaning Conditions on the Electrochemical Activity of Flux Residues under Surface Mount Components" at the Contamination, Cleaning and Coating Conference. The conference will take place May 22-24 at the Radisson Blu Hotel Amsterdam Airport Schiphol in Amsterdam, Netherlands. Click [here](#) for more information the technical conference.

If you have any questions, please contact [Michelle O'Brien](#).

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Kester is a global supplier of assembly materials for the Electronic Assembly and Semiconductor Packaging industries. Kester is focused on delivering innovative, robust and high-quality solutions to help our customers address their technological challenges. Kester's current product portfolio includes soldering attachment materials such as solder paste, soldering chemicals, TSF (tacky solder flux) materials, and metal products such as bar, solid and flux-cored wire. Kester is an Illinois Tool Works (ITW) company. ITW is a Fortune 200 company that produces engineered fasteners and components, equipment and consumable systems, and specialty products. It employs approximately 49,000 people, and is based in Glenview, Illinois, with operations in 57 countries.

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